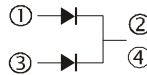
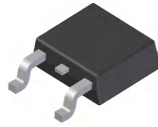


FEATURES

- * Low forward voltage drop
- * High current capability
- * High reliability
- * High surge current capability
- * Epitaxial construction

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Lead: Lead solderable per MIL-STD-202, method 208 guaranteed
- * Polarity: As Marked
- * Mounting position: Any



VOLTAGE RANGE

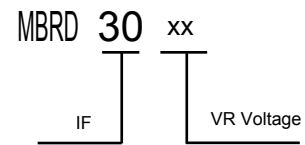
45 to 200 Volts

CURRENT

30.0 Ampere



LOGO GK xxx CODE



LEFT PIN RIGHT PIN BOTTOMSIDE HEAT SINK

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MBRD 3045	MBRD 3060	MBRD 30100	MBRD 30150	MBRD 30200	UNITS
Maximum Recurrent Peak Reverse Voltage	45	60	100	150	200	V
Maximum RMS Voltage	32	42	70	105	140	V
Maximum DC Blocking Voltage	45	60	100	150	200	V
Maximum Average Forward Rectified Current	30					A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	250					A
Maximum Instantaneous Forward Voltage at 30A	0.65	0.75	0.85	0.92		V
Maximum DC Reverse Current Ta=25°C	0.1		0.02			mA
at Rated DC Blocking Voltage Ta=125°C	5		2			mA
Typical Junction Capacitance (Note1)	570					pF
Typical Thermal Resistance R JA (Note 2)	2.5					°C/W
Operating Temperature Range Tj	-55 — +150					°C
Storage Temperature Range Tstg	-55 — +150					°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Ambient Vertical PC Board Mounting 0.5"(12.7mm) Lead Length.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

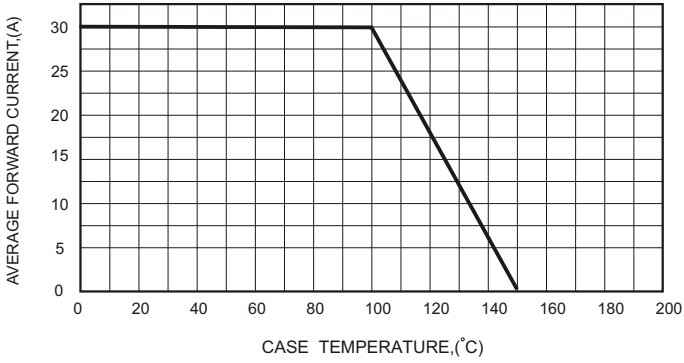


FIG.2-TYPICAL FORWARD CHARACTERISTICS

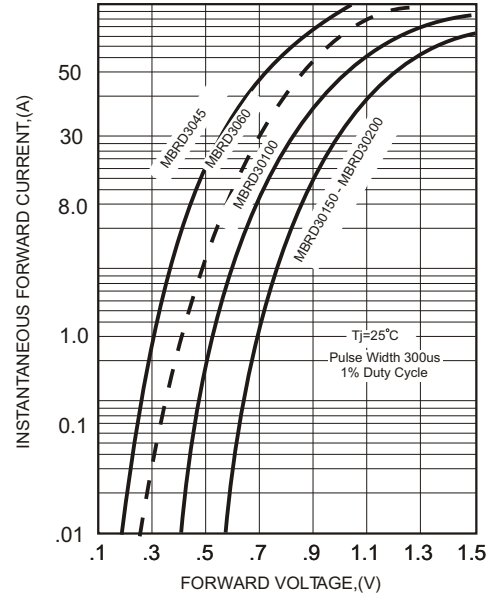


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

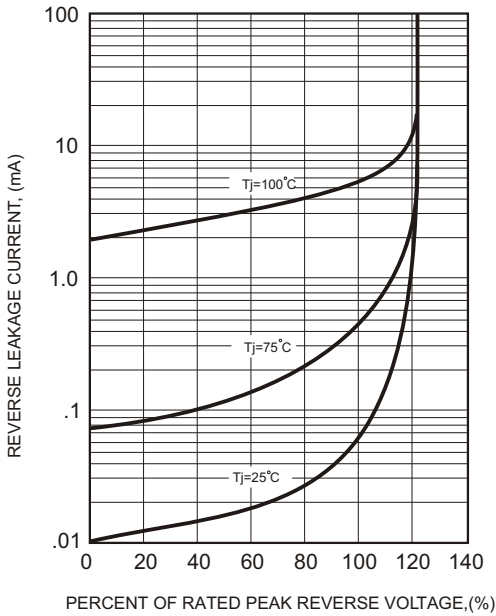


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

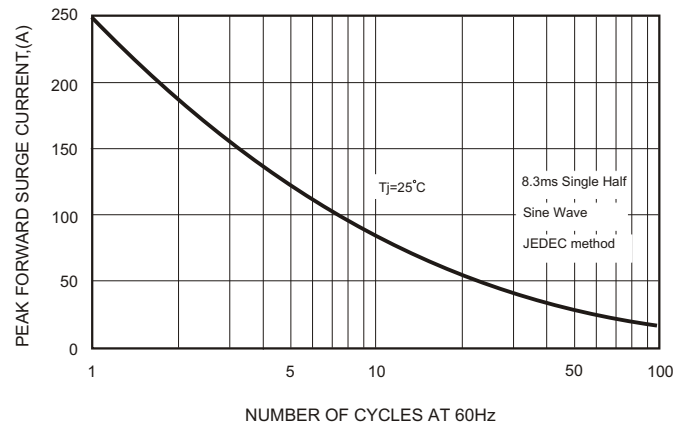
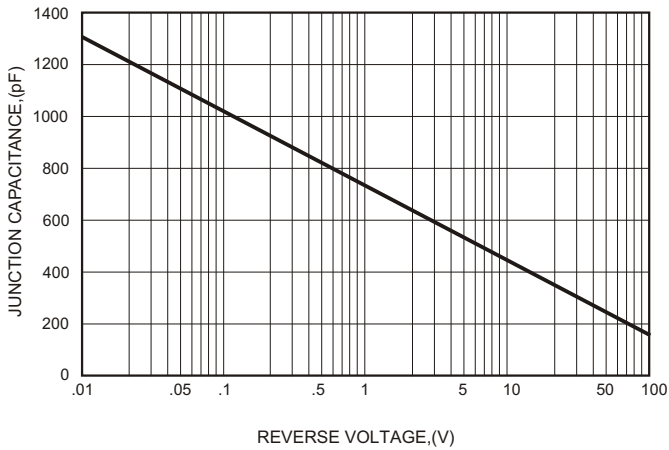


FIG.5-TYPICAL JUNCTION CAPACITANCE



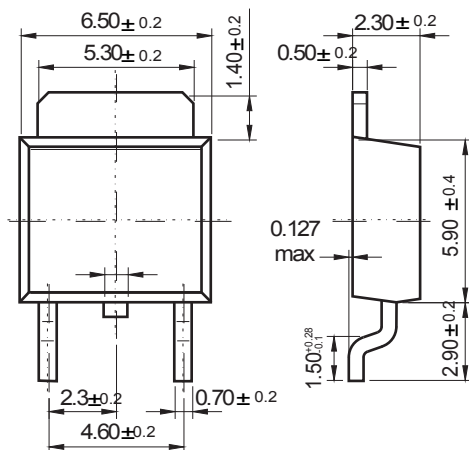
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

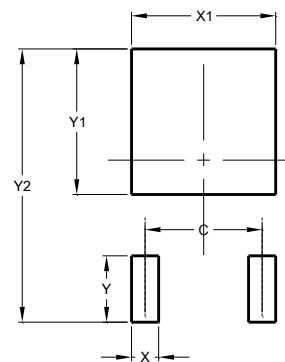


Package Dimensions & Suggested Pad Layout

TO-252



Dimensions in inches and (millimeters)



Dimensions	Value (in mm)
C	4.55
X	1.50
X1	5.80
Y	2.70
Y1	6.00
Y2	10.90

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.55±0.15
		D1	1.55±0.20
		E	1.75±0.20
		F	7.50±0.20
		W	16.00±0.20
		A0	7.10±0.20
		B0	10.50±0.20
		K0	2.70±0.20
		T	0.30±0.10
		D2	330.0±5.0
		D3	100.0±4.0
W1	20.0±5.0		
W2	25.0±5.0		
I	13.0±2.0		
Quantity: 2500PCS			

